



ALLIANCE MEMORY MATERIAL DECLARATION

**PART NUMBER:
AS4C256M32MD4-062BAN**

**Approved by:
Quality@AllianceMemory**

PART WEIGHT (mg)

306.751

No	Part Name	Material Name	Material Supplier	Material Content (Element)	CAS Number	Material Mass (mg)	Material Mass (%)	Substance wt (%)	Substance wt (mg)
1	Chip	Silicon	PSMC	Silica	7440-21-3	45.399	14.800%	100.00%	45.399
2	Substrate	Resin	Simmetch	Thermosetting resin with fiber glass	Trade secret	34.203	11.150%	22.60%	7.730
				Copper	7440-50-8			41.01%	14.026
				Au	7440-57-5			0.91%	0.311
				Nickel	7440-02-0			8.18%	2.798
				Acrylic resin	Trade secret			12.09%	4.135
				Epoxy resin	Trade secret			6.05%	2.068
				Talc containing no asbestos	14807-96-6			2.57%	0.878
				Barium Sulfate	7727-43-7			4.03%	1.379
				Silica, amorphous	7631-86-9			2.57%	0.878
3	Die attach film	Epoxy	Nitto	Synthetic rubber (Die attach film)	Trade secret	12.638	4.120%	5.00%	0.632
				Silica, amorphous(Die attach film)	7631-86-9 35-45			35.00%	4.423
				Phenol resin (Die attach film)	Trade secret			20.00%	2.528
				Epoxy resin (Die attach film)	Trade secret			20.00%	2.528
				Polypropylene copolymer (Dicing tape)	Trade secret			20.00%	2.528
4	Bonding wire	Metal	Tanaka	Au	7440-57-5	1.074	0.350%	99.00%	1.063
				Pd	7440-05-3			1.00%	0.011
5	Molding Compound	Resin	Hitachi	Epoxy Resin	Trade secret	185.584	60.500%	6.00%	11.135
				Phenol Resin	Trade secret			6.00%	11.135
				Carbon Black	1333-86-4			0.30%	0.557
				Silica	60676-86-0			87.70%	162.757
6	Solder ball	Metal	Senju	Sn	7440-31-5	27.853	9.080%	96.50%	26.878
				Ag	7440-22-4			3.00%	0.836
				Cu	7440-50-8			0.50%	0.139

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